S/N/10/723,474 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Suan J. Boon

Examiner: DiLinh Nguyen

Serial No.:

10/723,474

Group Art Unit: 2814

Filed:

November 26, 2003

Docket: 303.601US2

Title:

ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM

WAFER LEVEL PACKAGING

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No.

Filing Date

Attorney Docket

Title

10/722838

November

303.601US3

METHOD OF PACKAGING AT A

26, 2003 WAFER LEVEL

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicant requests that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

SUAN J. BOON

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 371-2157

Date 10 June 2005

David R. Cochran

Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this ______ day of _une, 2005.

Name Name

Signature

0/723,474

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

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Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

SUAN J. BOON

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

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Ting Kanut

Signature

PTO/SB/084(10-01)
Approved for use through 10/31/2002. OMB 651-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE
work Reduction Act of 1985, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO
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INFORMATION DISCLOSS... Complete if Known 10/723,474 **Application Number** November 26, 2003 **Filing Date** Boon, Suan **First Named Inventor** 2814 **Group Art Unit** Nguyen, DiLinh **Examiner Name** Attorney Docket No: 303.601US2 Sheet 1 of 1

US PATENT DOCUMENTS				
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-5,897,337	04/27/1999	Kata, K., et al.	09/25/1995
	US-6,013,944	01/11/2000	Moriya, S., et al.	08/18/1997
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